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Part Number: [0739434200](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, Solder Tail, Closed End, 72 Circuits

Documents:

[3D Model](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Drawing \(PDF\)](#)

Agency Certification

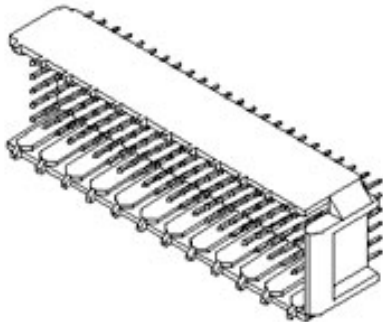
CSA LR19980
UL E29179

General

Product Family Backplane Connectors
Series [73943](#)
Application Backplane
Comments Solder Tail
Component Type PCB Header
Overview [hdm](#)
Product Name HDM®
Style N/A

Physical

Circuits (Loaded) 72
Circuits (maximum) 72
Color - Resin Black, Natural
Durability (mating cycles max) 250
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part No
Keying to Mating Part None
Material - Metal Phosphor Bronze
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
Number of Columns 12
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length (in) 0.118 In
PC Tail Length (mm) 3.00 mm
PCB Retention None
PCB Thickness Recommended (in) 0.098 In
PCB Thickness Recommended (mm) 2.50 mm
Packaging Type Tube
Pitch - Mating Interface (in) 0.079 In
Pitch - Mating Interface (mm) 2.00 mm
Plating min: Mating (µin) 30
Plating min: Mating (µm) 0.75
Plating min: Termination (µin) 100
Plating min: Termination (µm) 2.5
Stackable Yes
Surface Mount Compatible (SMC) Yes
Temperature Range - Operating -55°C to +105°C



Series

image - Reference only

EU RoHS

**ELV and RoHS
Compliant**
**REACH SVHC
Contains SVHC: No**
**Halogen-Free
Status**

China RoHS



Not Reviewed

**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series

[73943Series](#)

Mates With

[73632](#) HDM PLUS® Board-to-Board
Daughtercard Receptacle. [73780](#) HDM®
Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

*Tooling specifications and manuals are
found by selecting the products below.
Crimp Height Specifications are then
contained in the Application Tooling
Specification document.*

Global

Description	Product #
HDM® Backplane	0621001400
Insertion Signal	
Contact Tool	
Extraction Tool	0621001000

Termination Interface: Style	Through Hole
Electrical	
Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Voltage - Maximum	250V AC
Solder Process Data	
Duration at Max. Process Temperature (seconds)	40
Lead-free Process Capability	SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	3
Process Temperature max. C	260
Material Info	
Reference - Drawing Numbers	
Packaging Specification	PK-70873-0818
Sales Drawing	SD-73943-001

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This document was generated on 05/14/2010

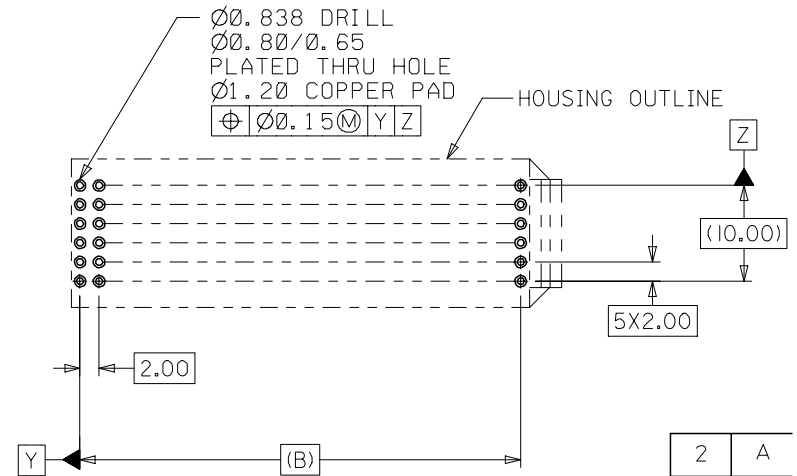
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NOTES:

1. MATERIALS: HOUSING--LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, UL94V-0, COLOR: BLACK.
TERMINAL: PHOSPHOR BRONZE.
2. FINISH: 0.75 MICROMETERS MINIMUM SELECTIVE GOLD (Au) IN MATING AREA
2.50 MICROMETERS MINIMUM SELECTIVE TIN (Sn) IN TAIL AREA
NICKEL (Ni) UNDERPLATE OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. PACKAGE PER PK-70873-0818.
6. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.



SEE NOTE 6


 PCB LAYOUT: COMPONENT SIDE
 RECOMMENDED PCB THICKNESS: 2.50 MIN

2	A
1	G
SHT	REV

 MODIFY FINISH NOTE
 EC NO: UCP2007-2259
 IDRW:MSI:BARRA 2007/03/13
 CHKD:BBARKER 2007/03/21
 APPR:SMILLER 2007/03/22

 QUALITY SYMBOLS
 ▽=0
 ▽=0
 DESCRIPTION
 REV

 GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	±---	±---
3 PLACES	±---	±---
2 PLACES	±0.05	±---
1 PLACE	±0.10	±---
ANGULAR ±1/2°		

 DRAFT WHERE APPLICABLE
 MUST REMAIN
 WITHIN DIMENSIONS

 DIMENSION STYLE
 MM ONLY
 DRAWN BY
 JB INGHAM
 DATE
 1998/01/13
 CHECKED BY
 SREED
 DATE
 1998/01/13
 APPROVED BY
 CBIXLER
 DATE
 1998/01/13
 MATERIAL NO.
 SEE CHART

 SCALE
 2:1
 DESIGN UNITS
 METRIC
 THIRD ANGLE
 PROJECTION
 TITLE
 SALES ASSY HDM BACKPLANE
 END WALL OPTION
 SOLDER TAIL VERSION
 MOLEX INCORPORATED
 DOCUMENT NO.
 SD-73943-001
 SHEET NO.
 1 OF 2

MATERIAL NUMBER ASSIGNMENT

73943-* * 0 0

NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "H"
0	72	27.6	22.00	2.0
1	144	51.6	46.00	2.0
2	72	27.6	22.00	2.5
3	144	51.6	46.00	2.5
4	72	27.6	22.00	3.0
5	144	51.6	46.00	3.0
6	72	27.6	22.00	3.5
7	144	51.6	46.00	3.5

NUMBER	DIM "M"
0	5.0
1	5.5
2	6.0

SEE SHEET 1 EC NO. U81577 DRWN:JBINGHAM 98/02/03 CHK: REED 98/02/03 APPR:CBIXLER 98/02/03 A	DESCRIPTION REV	QUALITY SYMBOLS MAJOR CRITICAL	GENERAL TOLERANCES: (UNLESS SPECIFIED)		SCALE NO:NE	DESIGN UNITS ☒ mm ☐ INCH	THIRD ANGLE PROJECTION	DIMENSIONS: ☐ mm ☐ INCH ☒ mm ONLY		SHT	REV	
					DRAWN BY & DATE JBINGHAM 98/01/13	TITLE: SALES ASS'Y, HDM BACKPLANE END WALL OPTION SOLDER TAIL VERSION MOLEX INCORPORATED		MATERIAL NO. SEE CHART	DRAWING NO. SD-73943-001	SHEET NO. 2	SIZE B	
					CHECKED BY & DATE SREED 98/01/13							
					APPROVED BY & DATE CBIXLER 98/01/13							
					CAD FILENAME S73943X2.DGN							
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.								

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<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

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Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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